

Page 0001 11/23/88 14:34:29 Tx: AM27LS00 TED - Ft: AMD FMT

Am27LS00 Series

256-Bit Low-Power Schottky Bipolar RAM

DISTINCTIVE CHARACTERISTICS

- High speed
- Internal ECL circuitry for optimum speed/power performance over voltage and temperature
- Output preconditioned during write to eliminate the write recovery glitch
- Available with three-state outputs or with open-collector outputs

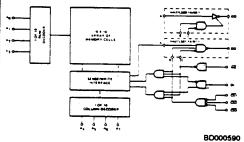
GENERAL DESCRIPTION

The Am27LS00 Family is comprised of fully decoded bipolar random-access memories for use in high-speed buffer memories. The memories are organized 256-words by 1-bit with an 8-bit binary address field and separate data in and data output lines. The memories have three active LOW chip select inputs and a three-state output (Am27LS00 devices). All inputs are buffered to present an input load of only 0.5 TTL unit loads.

Read/write operation is controlled by an active LOW write enable input. When the write enable is LOW and the chip is

selected the data on the data input is written into the location specified by the address inputs. During this operation the output of the -1 device is active and inverts the value of DI (Write Transparent Operation). The other devices disable the output during the period WE is low. Reading is accomplished by having the chip selected and the write enable input HIGH. Data stored in the location specified by the address inputs is read out and appears on the data output inverted.

BLOCK DIAGRAM



MODE SELECT TABLE

	Input		Data Output	
ĊŚ	WE	DI	Status DO (tn+ 1)	Mode
Н	X	Х	Output Disabled	No Selection
L	L	L	Inverted/Disabled*	Write '0'
L	٦	н	Inverted/Disabled*	Write '1'
L	н	х	Selected Bit (Inverted)	Read

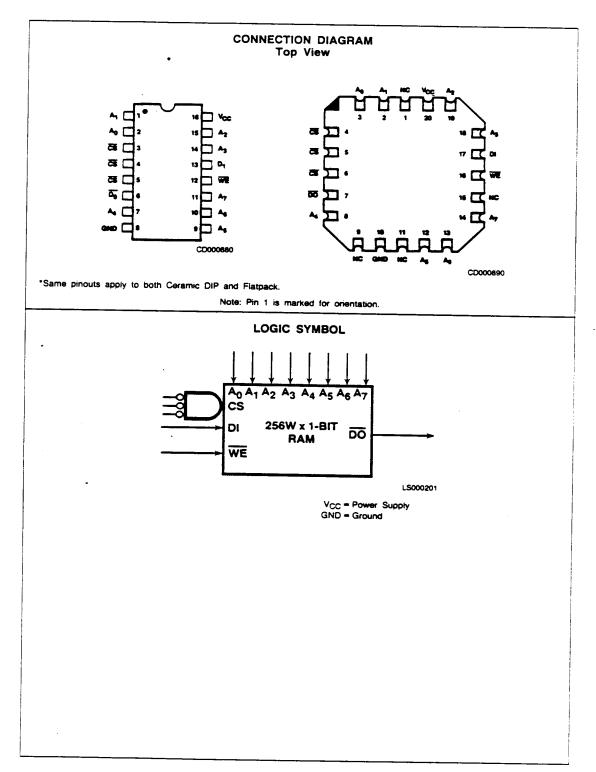
H = HIGH L = LOW X = Don't Care *Inverted = -1 Devices Disabled = All Other Devices

PRODUCT SELECTOR GUIDE

Three-State	STD	Am27LS00A	Am27LS00	Am27LS00A	Am27LS00	
Part Number	Write Transparent		Am27LS00-1		Am27LS00-	
Access Time		35 ns	1	15 ns	55 ns	
Temperature Range		С	С	М	М	

Publication # Rev Amendment
03233 E /0
Issue Date: January 1989





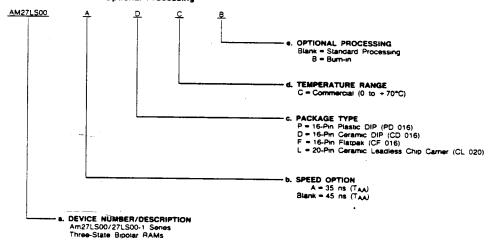


ORDERING INFORMATION

Standard Products

AMD standard products are available in several packages and operating ranges. The order number (Valid Combination) is formed by a combination of: a. Device Number

- b. Speed Option (if applicable)
- c. Package Type
- d. Temperature Range
- e. Optional Processing



Valid Combinations								
AM27LS00								
AM27LS00A	PC, PCB, DC, DCB, FC, FCB,							
AM27LS00-1								

Valid Combinations

Valid Combinations list configurations planned to be supported in volume for this device. Consult the local AMD sales office to confirm availability of specific valid combinations, to check on newly released combinations, and to obtain additional data on AMD's standard military grade products.

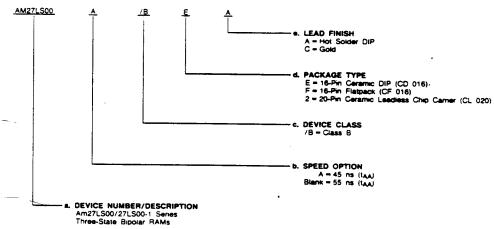


MILITARY ORDERING INFORMATION

APL Products

AMD products for Aerospace and Defense applications are available in several packages and operating ranges. APL (Approved Products List) products are fully compliant with MiL-STD-883C requirements. The order number (Valid Combination) for APL products is formed by a combination of: a. Device Number

- b. Speed Option (if applicable)
- c. Device Class
- d. Package Type
- e. Lead Finish



Valle	d Combinations
AM27LS00	
AM27LS00A	/BEA,./BFA, /B2C
AM27LS00-1	7

Valid Combinations

Valid Combinations list configurations planned to be supported in volume for this device. Consult the local AMD sales office to confirm availability of specific valid combinations or to check for newly released valid combinations.

Group A Tests

Group A tests consist of Subgroups 1, 2, 3, 7, 8, 9, 10, 11.



ABSOLUTE MAXIMUM RATINGS

Storage Temperature65 to +150°C
Ambient Temperature with
Power Applied55 to +125°C
Supply Voltage to ground potential
(Pin16 to Pin8) continuous0.5 V to +7.0 V
DC Voltage Applied to Outputs
for High Output State0.5 V to+ VCCmax
DC Input Voltage0.5 V to +Vcc
Output Current, into Outputs30 mA
DC Input Current30 mA to +5 mA
Stresses above those listed under ABSOLUTE MAXIMUM
RATINGS may cause permanent device failure. Functionality
at or above these limits is not implied. Exposure to absolute
maximum ratings for extended periods may affect device

reliability.

OPERATING RANGES

Commercial (C) Devices	
Temperature	0 to +75°C
Supply Voltage	
Military (M) Devices	
Temperature	55 to +125°C
Supply Voltage	

Operating ranges define those limits between which the functionality of the device is guaranteed.

(See Note 4)

DC CHARACTERISTICS over operating range unless otherwise specified (for APL Products, Group A, Subgroups 1, 2, 3 are tested unless otherwise noted)

Parameter Symbol	* Parameter Description	Test Conditions				Typ. (Note 1)	Max.	Unit
VOH (Note 2)	Output HIGH Voitage	VCC = Min.,	COM'L			$\overline{}$		
	Output Trick Voltage	VIN - VIH OF VIL	IOH = - 2.0 mA	MIL	2.4	3.2		V
VOL.	Output LOW Voltage	VCC = Min., VIN = VIH or VIL				0.3	0.45	V
VIH	Input HIGH Level	Guaranteed input lo (Note 3)	Guaranteed input logical HIGH voltage for all inputs (Note 3)					v
VIL	Input LOW Level	Guaranteed input logical LOW voltage for all inputs (Note 3)					0.8	V
ii <u>L</u>	Input LOW Current	V _{CC} = Max., V _{IN} = 0.40 V				- 0.030	- 0.25	mA
чн	Input HIGH Current	V _{CC} = Max., V _{IN} = 2.7 V				<u> </u>	20	Αμ
SC (Note 2)	Output Short Circuit Current	V _{CC} = Max., V _{OUT} = 0.0 V				-30	-60	mA
icc	Power Supply Current	All inputs = GND		"A" version		80	115	
		V _{CC} = Max. Standard				55	70	mA
VCL	Input Clamp Voltage	V _{CC} = Min., I _{IN} = -1	VCC = Min., I _{IN} = -18 mA				-1.2	v
CEX	Output Leakage Current VCS = VIH or VWE = VIL VOUT = 2.4 V					0	30	Aμ
		VCS = VIH OF VWE =	- 30	0		μА		

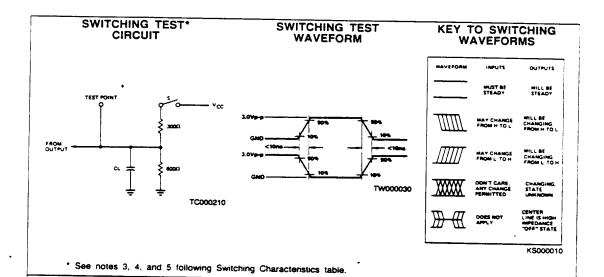
Notes: 1. Typical limits are at VCC = 5.0V and T_A = 25°C.

2. This applies to three-state devices only.

3. These are absolute voltages with respect to device ground pin and include all overshoots due to system and/or tester noise. Do not attempt to test these values without suitable equipment.

4. Operating Specification with adequate time for temperature is stabilization and transverse air flow exceeding 400 linear feet per minute. Conformance testing performed instantaneously where T_A = T_C=T_J 0_JA = 44 - 59° c/w (with moving air) for ceramic DIPs 0_JC = 10 - 17° c/w for flatpack or leadless chip carners.





SWITCHING CHARACTERISTICS over operating range unless otherwise specified (for APL Products, Group A, Subgroups 9, 10, 11 are tested unless otherwise noted).

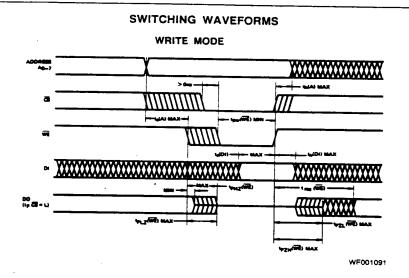
No.	Parameter Symbol	Parameter Description	Am27LS00A/Family				Am27S00/Family				Ī
			C Devices		M Devices		C Devices		M Devices		1
			Min.	Max.	Min.	Max,	Min.	Max.	Min.	Max.	Unit
1	tp _{LH} (A)	Delay from Address to Output			†		 	-			
2	tpHL(A)	- Soldy work Address to Corpor		35		45	ļ	45		55	ns
3	tpzH(CS)	Delay from Chip Select (LOW) to					<u> </u>	 		 	
4	tpZL(CS)	to Active Output and Correct Data		25		25		25	İ	30	ns
5	tpZH(WE)	Delay from Write Enable (HIGH)				45					<u> </u>
6	tezL(WE)	to Active Output and Correct Data		35				45		55	ns
7	t _s (A)	Setup Time Address (Prior to initiation of Write)	0		5		0		5		ns
8	th(A) -	Hold Time Address (After Termination of Write)	0		5		0		5		ns
9	t _s (DI)	Setup Time Data Input (Prior to Termination of Write)	25		30	-	30		35		ns
10	th(OI)	Hold Time Data Input (After Termination of Write)	0		5		0		5		ns
11	t _{pw} (WE)	Min Write Enable Pulse Width to Insure Write	25		30		30		35		ns
12	tpHZ(ČŠ)	Delay from Chip Select (HIGH)									
13	tp <u>LZ</u> (CS)	to inactive Output (HI-Z)		25	ĺ	25		25		30	ns
14	tpt_Z(WE)	Delay from Write Enable (LOW)									
15	tpH2(WE)	to inactive Output (HI-Z) (Note 6)	1 !	30		40		30	ŀ	40	ns

Notes: 1. Typical limits are at V_{CC} = 5.0 V and T_A = 25°C.

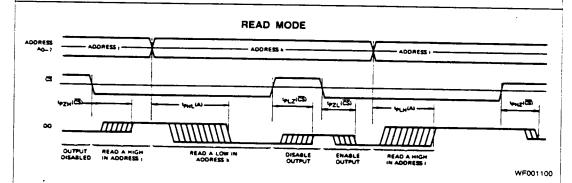
2. Output is preconditioned to data in (inverted) during write to insure correct data is present on all outputs when write is terminated.

Output is preconditioned to data in (inverted) during write to insure correct data is present on all outputs when write is terminated. (No write recovery glitch.)
 tp_H(A) and tpHL(A) are tested with S closed an d C_L = 50 pF with both input and output timing referenced to 1.5 V.
 For open collector, all delays from write Enable(WE) oir Chip Select(CS) inputs to the Data Output(DOUT). tp_Z(WE). tp_Z(CS). tp_Z(WE) and tpZL(CS) are measured with S closed and C_L = 50 pF and with both the input and output timing referenced to 1.5 V. tpZ(WE) and tpZ(CS) are measured with S closed. C_L = 50 pF and with both the input and output timing referenced to 1.5 V. tpZ(WE) and tpZ(CS) are measured with S closed. C_L = 50 pF and with both the input and output timing referenced to 1.5 V. tpZ(WE) and tpZ(CS) are measured with S closed. C_L = 50 pF and with both the input and output timing referenced to 1.5 V. tpZ(WE) and tpZ(CS) are measured with S closed. C_L ≤ 5 pF and are measured between the 1.5 V level on the input and the V_{OL} +500 mV level on the output.
 Does not apply to -1 devices.





Write Cycle Timing. The cycle is initiated by an address change. After $t_s(A)$ max, the write enable may begin. The chip select must also be LOW for writing. Following the write pulse, $t_h(A)$ max must be allowed before the address may be changed again. The output will be inactive (floating for the Am27LS00A/00) while the write enable is LOW. Ordinanly, the chip select should be LOW during the entire write pulse.



Switching delays from address and chip select inputs to the data output. For the Am27LS00A/00, Am27LS00-1A/00-1 disabled output is "OFF," represented by a single center line.